(a) a support structure adapted for engagement with a semiconductor chip having a top surface, a bottom surface, and a gap extending through said support structure between said surfaces and defining first and second portions of said support structure on opposite sides of the gap;

(b) at least one elongated bus disposed alongside said gap, on said second portion of said support structure; and

(c) a plurality of electrically conductive leads, each said lead having a connection section extending across said gap, said connection section having a first end disposed on the first portion of the support structure, and a second end secured to said bus, and a frangible section; said gap being open at said bottom surface of said support structure, said leads being adapted to be bonded to contacts on a semiconductor chip disposed beneath said bottom surface by breaking the frangible sections of said leads so as to disconnect said second ends of said leads from the bus and engage the leads with the contacts of the chip.

10. (Amended) The component of claim 1, wherein the support structure includes a dielectric layer, said dielectric layer including first and second portions, said first portion of said support structure including said first portion of said dielectric layer, said second portion of said support structure including said second portion of said dielectric layer.

13. (Amended) The component of claim 11, wherein the support structure includes a dielectric layer defining said top surface of said support structure and said compliant layer defining said bottom surface of said support structure.

17. (Thrice Amended) A component as claimed in claim 1, wherein said gap includes a plurality of elongated slots extending substantially around said first portion so that the slots are disposed between the first portion and the second portion, the component including a plurality of said elongated buses arranged on said second portion so that one such bus extends alongside each said slot.

19. (Thrice Amended) The component as claimed in claim 18, wherein said slots are connected to one another to form a substantially continuous channel surrounding said first portion, said first portion being connected to said second portion only through said leads, whereby said first portion will be detached from said second portion upon breakage of said frangible sections.

20. (Amended) The component of claim 1, wherein said first and second portions of said support structure comprise a unitary support.

25. (Amended) The component of claim 1, wherein said frangible sections overlie said gap, at least one of said first and second ends of each said connection section is displaceable within said gap relative to said support structure upon severing said frangible section while leaving a remainder of said connection section intact.

Insert new claims 26-27 as follows:

26. (New) The component of claim 1 further comprising terminals disposed on said first portion of support structure, at least some of said leads having their first ends connected to said terminals.

27. (New) A semiconductor chip mounting component comprising:

(a) a support structure adapted for engagement with a semiconductor chip having a top surface, a bottom surface, and a gap extending through said support structure between said surfaces and defining first and second portions of said support structure on opposite sides of said gap;

(b) a plurality of electrically conductive leads, each said lead having a connection section extending across said gap, said connection section having a first end disposed on the first portion of the support structure, a second end secured to said bus, and a frangible section, wherein said frangible section is disconnectable from one side of said first and second ends upon application of a force to said connection section;

(c) said gap being open at said bottom surface of said support structure, said leads being adapted to be bonded to contacts on a semiconductor chip disposed beneath said bottom surface by breaking the frangible section of said leads so as to disconnect said second ends of said leads from said bus and engage said leads with the contacts of the chips, said frangible section is mechanically weaker than said first and second ends of said connection section;

(d) terminals disposed on said first portion of support structure, wherein at least some of said leads having their first ends connected to said terminals.